

Title (en)

THERMAL VACUUM DEPOSITION METHOD AND DEVICE

Title (de)

VERFAHREN UND VORRICHTUNG ZUR THERMISCHEN VAKUUMBESCHICHTUNG

Title (fr)

PROCEDE ET DISPOSITIF POUR LE REVETEMENT THERMIQUE SOUS VIDE

Publication

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Application

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Abstract (en)

[origin: WO2005106072A2] The invention relates to a thermal vacuum deposition device and method in which a band-shaped substrate is continuously conveyed in a vaporization channel that is charged with a vaporous coating material. The aim of the invention is to allow the substrate to be quickly protected against damage during the coating process in previously known deposition methods and devices. Said aim is achieved by the inventive method, which is characterized in that the vaporization channel is sealed by inserting at least one positionally adjustable hollow element into an outer space of the vaporization channel and an inner space of the vaporization channel when a minimum conveying speed is not attained or when the substrate is at a standstill such that the substrate is located in the inner space.

IPC 8 full level

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